

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	92648	inspect\$3 and(wafer\$I or semiconductor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:49
L3	57	inspect\$3 and formation adj state and(wafer\$I or semiconductor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:50
L4	45	L3 and(@ad< "20031222" or @riad< "20031222" or @prad< "20031222" or @ptad< "20031222")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:54
L5	39	L3 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:54
L6	0	L5 and generat\$3 and inspect \$3 adj data same pattern adj area same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:56
L7	2	inspect\$3 adj data same pattern adj area same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:57
L8	39	L5 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:57
L9	0	L8 and inspect\$3 adj data same pattern adj area same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:58

L10	0	L8 and inspect\$3 adj data and pattern adj area and inside and outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:58
L11	4	L8 and inspect\$3 and pattern adj area and inside and outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:59
L12	4	L11 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:59
L13	4	L12 and inside and outside	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:03
L14	4	L12 and inside and outside and pattern adj(area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:04
L15	4	L12 and inside and outside and pattern adj(area or regions)and(comapar\$5 or match\$ or combining)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:05
L16	4	L12 and inside and outside and pattern adj(area or regions)and(comapar\$5 or match\$ or combining)and (difference or differ or sum) and(luminance or shapes)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:07
L17	109	("5723236" "4783826" "5608816" "5892224" "5917590" "6166808" "4319270" "4760265" "4897795" "4943186" "5324568" "5331432" "5362591" "5404410" "5621825" "5656397" "5659172" "5665645" "5691543" "5838433" "5885735" "6038015" "6043870" "6052170" "6219807" "6219807" "3806015" "4056716" "4156231" "4244650" "4247748" "4255055" "4270863" "4286266" "4286146" "4295200" "4296474" "4297818"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:20

		"4311267" "4318590" "4319269" "4320567" "4321534" "4330775" "4339952" "4344146" "4357540" "4365163" "4366564" "4396509").pn.				
L18	0	L17 and inspect\$3 and formation adj state and(wafer \$I or semiconductor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:23
L19	0	L17 and inspect\$3 adj data same pattern adj area same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:24
L20	22	L17 and inspect\$3 and(wafer \$I or semiconductor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:25
L21	22	L20 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:25
L22	92648	inspect\$3 and(wafer\$I or semiconductor\$I or chip\$I or substrat\$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:50
L23	2	L22 and(generat\$3 or obtaining)and inspect\$3 adj data same pattern adj area same inside adj pattern same outside adj pattern and inspect \$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:52
L24	2	L22 and(generat\$3 or obtaining)and inspect\$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:53

L25	2	(generat\$3 or obtaining)and inspect\$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:53
L26	20	(generat\$3 or obtaining)and inspect\$3 and(region or area) adj pattern and inside adj pattern and outside adj pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:55
L27	14	L26 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:55
L28	0	L8 and inspect\$3 adj data same pattern adj area same object same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:19
L29	0	L26 and inspect\$3 adj data same pattern adj area same object same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:19
L30	1	L26 and inspect\$3 adj data and pattern adj area and (object or patterns)same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:20
L31	0	L30 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:20
L32	5	L2 and inspect\$3 adj data and pattern adj area and(object or patterns)same inside same outside and inspect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:21
L33	3	L32 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:21

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